

SN54ALS32, SN54AS32, SN74ALS32, SN74AS32 QUADRUPLE 2-INPUT POSITIVE-OR GATES

SDAS113B – APRIL 1982 – REVISED DECEMBER 1994

- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

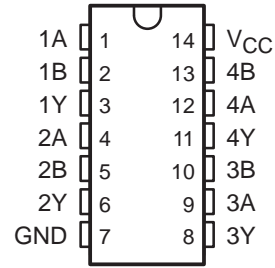
These devices contain four independent 2-input positive-OR gates. They perform the Boolean functions $Y = A \bullet B$ or $Y = A + B$ in positive logic.

The SN54ALS32 and SN54AS32 are characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ALS32 and SN74AS32 are characterized for operation from 0°C to 70°C .

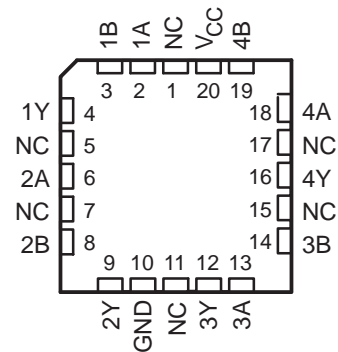
FUNCTION TABLE
(each gate)

INPUTS		OUTPUT
A	B	Y
H	X	H
X	H	H
L	L	L

SN54ALS32, SN54AS32 . . . J PACKAGE
SN74ALS32, SN74AS32 . . . D OR N PACKAGE
(TOP VIEW)

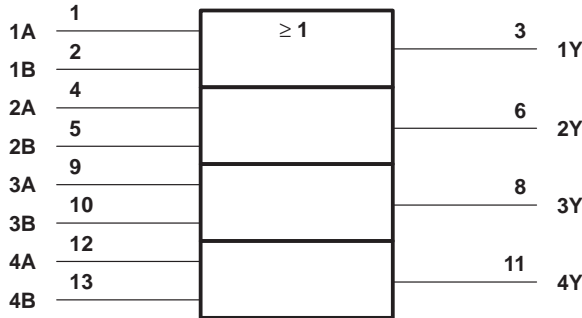


SN54ALS32, SN54AS32 . . . FK PACKAGE
(TOP VIEW)

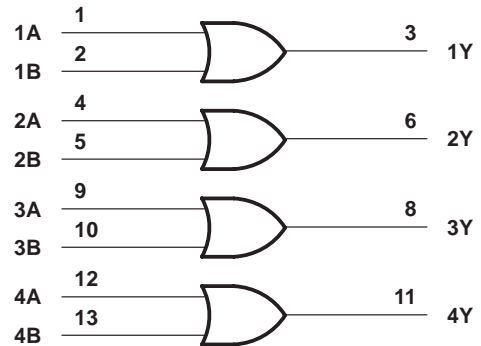


NC – No internal connection

logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the D, J, and N packages.

SN54ALS32, SN54AS32, SN74ALS32, SN74AS32 QUADRUPLE 2-INPUT POSITIVE-OR GATES

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC}	7 V
Input voltage, V_I	7 V
Operating free-air temperature range, T_A : SN54ALS32	-55°C to 125°C
SN74ALS32	0°C to 70°C
Storage temperature range	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54ALS32			SN74ALS32			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{OH}	High-level output current			-0.4			-0.4	mA
I_{OL}	Low-level output current			4			8	mA
T_A	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54ALS32			SN74ALS32			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	$V_{CC} = 4.5 V$, $I_I = -18 mA$			-1.5			-1.5	V
V_{OH}	$V_{CC} = 4.5 V$ to $5.5 V$, $I_{OH} = -0.4 mA$	$V_{CC} - 2$			$V_{CC} - 2$			V
V_{OL}	$V_{CC} = 4.5 V$	$I_{OL} = 4 mA$		0.25	0.4	$I_{OL} = 4 mA$		V
		$I_{OL} = 8 mA$				0.35	0.5	
I_I	$V_{CC} = 5.5 V$, $V_I = 7 V$			0.1			0.1	mA
I_{IH}	$V_{CC} = 5.5 V$, $V_I = 2.7 V$			20			20	μA
I_{IL}	$V_{CC} = 5.5 V$, $V_I = 0.4 V$			-0.1			-0.1	mA
$I_{OS}§$	$V_{CC} = 5.5 V$, $V_O = 2.25 V$	-20		-112	-30		-112	mA
I_{CCH}	$V_{CC} = 5.5 V$, $V_I = 4.5 V$		1.9	4		1.9	4	mA
I_{CCL}	$V_{CC} = 5.5 V$, $V_I = 0$		2.6	4.9		2.6	4.9	mA

‡ All typical values are at $V_{CC} = 5 V$, $T_A = 25°C$.

§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS} .

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5 V$ to $5.5 V$, $C_L = 50 pF$, $R_L = 500 \Omega$, $T_A = MIN$ to MAX ††				UNIT
			SN54ALS32		SN74ALS32		
			MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	3	18	3	14	ns
t_{PHL}			3	16	3	12	

†† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



SN54ALS32, SN54AS32, SN74ALS32, SN74AS32 QUADRUPLE 2-INPUT POSITIVE-OR GATES

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC}	7 V
Input voltage, V_I	7 V
Operating free-air temperature range, T_A : SN54AS32	-55°C to 125°C
SN74AS32	0°C to 70°C
Storage temperature range	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54AS32			SN74AS32			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{OH}	High-level output current			-2			-2	mA
I_{OL}	Low-level output current			20			20	mA
T_A	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54AS32			SN74AS32			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	$V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$			-1.2			-1.2	V
V_{OH}	$V_{CC} = 4.5\text{ V to } 5.5\text{ V}$, $I_{OH} = -2\text{ mA}$	$V_{CC} - 2$			$V_{CC} - 2$			V
V_{OL}	$V_{CC} = 4.5\text{ V}$, $I_{OL} = 20\text{ mA}$	0.35	0.5		0.35	0.5		V
I_I	$V_{CC} = 5.5\text{ V}$, $V_I = 7\text{ V}$		0.1			0.1		mA
I_{IH}	$V_{CC} = 5.5\text{ V}$, $V_I = 2.7\text{ V}$		20			20		μA
I_{IL}	$V_{CC} = 5.5\text{ V}$, $V_I = 0.4\text{ V}$		-0.5			-0.5		mA
I_{O}^{\S}	$V_{CC} = 5.5\text{ V}$, $V_O = 2.25\text{ V}$	-30	-112		-30	-112		mA
I_{CCH}	$V_{CC} = 5.5\text{ V}$, $V_I = 4.5\text{ V}$		7.3	12		7.3	12	mA
I_{CCL}	$V_{CC} = 5.5\text{ V}$, $V_I = 0$		16.5	26.6		16.5	26.6	mA

‡ All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS} .

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5\text{ V to } 5.5\text{ V}$, $C_L = 50\text{ pF}$, $R_L = 500\ \Omega$, $T_A = \text{MIN to MAX}^{\parallel}$				UNIT
			SN54AS32		SN74AS32		
			MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	1	7.5	1	5.8	ns
t_{PHL}			1	6.5	1	5.8	

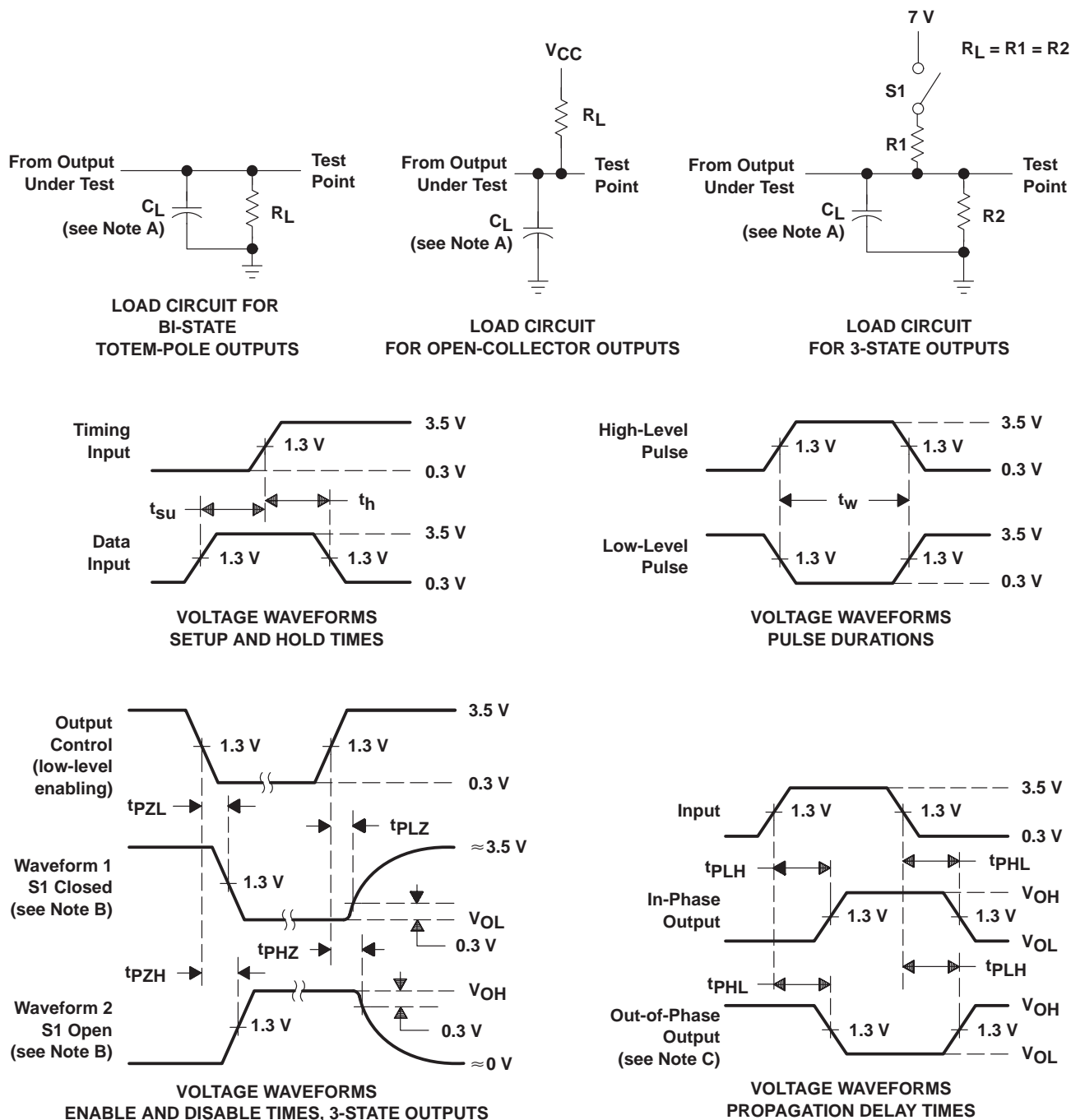
[¶] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



SN54ALS32, SN54AS32, SN74ALS32, SN74AS32 QUADRUPLE 2-INPUT POSITIVE-OR GATES

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PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
 D. All input pulses have the following characteristics: $PRR \leq 1$ MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-86836012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-8683601DA	ACTIVE	CFP	W	14	1	TBD	Call TI	Call TI	
5962-9756001Q2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-9756001QCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Call TI	
JM38510/37501B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/37501BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
M38510/37501B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
M38510/37501BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN54ALS32J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN54AS32J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN74ALS32D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS32DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS32DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS32DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS32DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS32DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS32N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS32N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74ALS32NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS32NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS32NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS32NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74AS32D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS32DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS32DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS32DBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS32DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS32DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS32DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS32DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS32DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS32N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS32N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74AS32NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS32NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS32NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS32NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SNJ54ALS32FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54ALS32J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ54ALS32W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
SNJ54AS32FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54AS32J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	

⁽¹⁾ The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN54ALS32, SN54AS32, SN74ALS32, SN74AS32 :

● Catalog: [SN74ALS32](#), [SN74AS32](#)

● Military: [SN54ALS32](#), [SN54AS32](#)

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

● Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS32DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ALS32NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AS32DBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74AS32DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AS32NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS32DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74ALS32NSR	SO	NS	14	2000	367.0	367.0	38.0
SN74AS32DBR	SSOP	DB	14	2000	367.0	367.0	38.0
SN74AS32DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74AS32NSR	SO	NS	14	2000	367.0	367.0	38.0

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

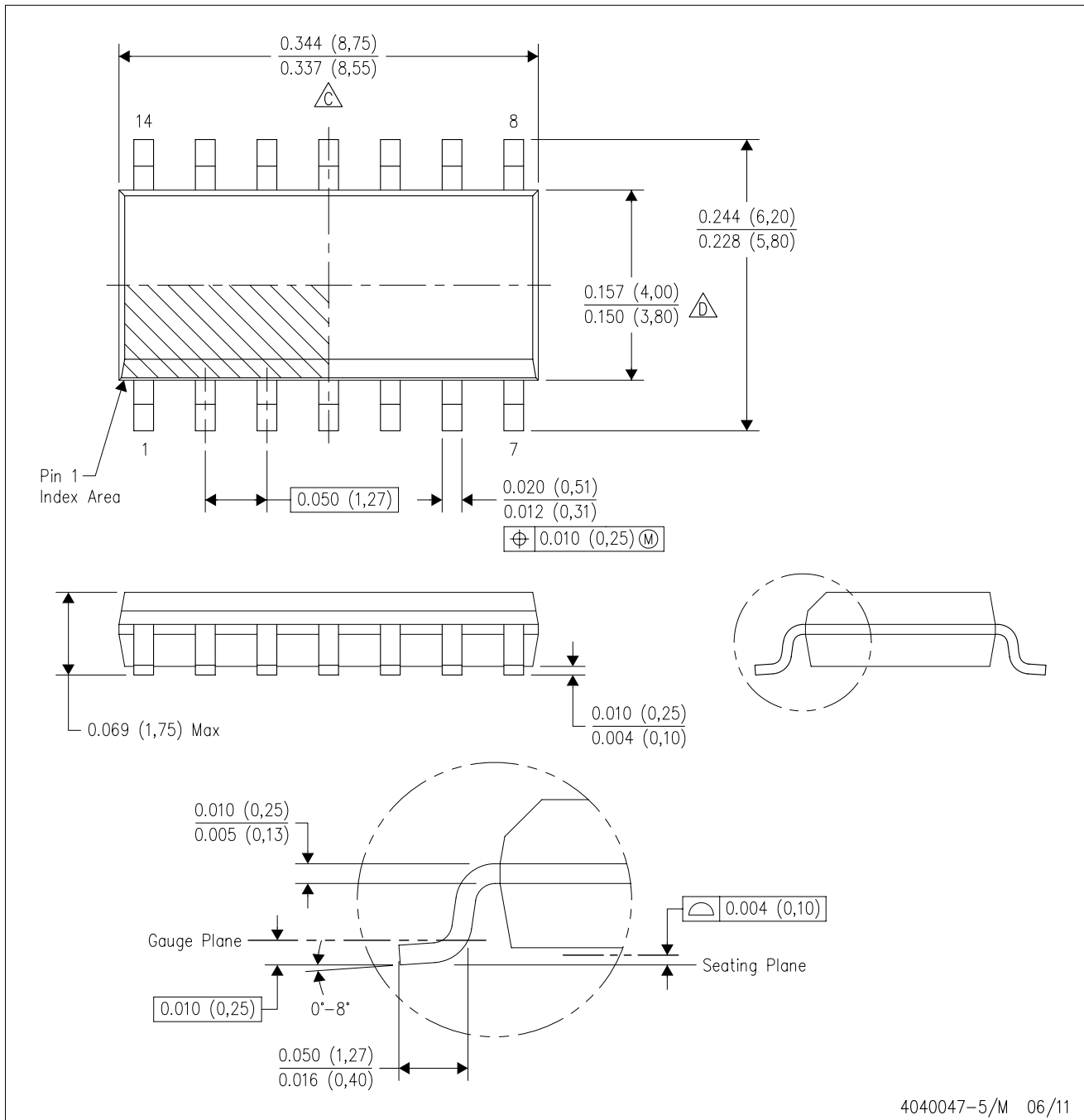
16 PINS SHOWN





- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4040047-5/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 -  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

IMPORTANT NOTICE

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